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Diodes Incorporated DMN3025LFG-7

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Datasheet of DMN3025LFG-7 - MOSFET N CH 30V 7.5A POWERDI

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DMN3025LFG

# 30V N-CHANNEL ENHANCEMENT MODE MOSFET POWERDI®

# **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D Max</sub> T <sub>A</sub> = +25°C
30V	18mΩ @ V <sub>GS</sub> = 10V	7.5A
300	28mΩ @ V <sub>GS</sub> = 4.5V	6.1A

# **Description**

This MOSFET has been designed to minimize the on-state resistance  $(R_{DS(on)})$  and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

# **Applications**

- Backlighting
- · Power Management Functions
- DC-DC Converters

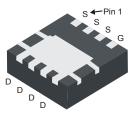
### **Features**

- Low R<sub>DS(ON)</sub> ensures on state losses are minimized
- Small form factor thermally efficient package enables higher density end products
- Occupies just 33% of the board area occupied by SO-8 enabling smaller end product
- 100% Unclamped Inductive Switch (UIS) test in production
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: POWERDI3333-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish Matte Tin annealed over Copper leadframe.
  Solderable per MIL-STD-202, Method 208 <sup>(3)</sup>
- Weight: 0.072 grams (approximate)

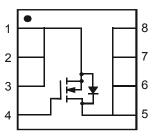
#### POWERDI3333-8



Bottom View



Top View



Top View Internal Schematic

# **Ordering Information** (Note 4)

Part Number	Case	Packaging
DMN3025LFG-7	POWERDI3333-8	2000/Tape & Reel
DMN3025LFG-13	POWERDI3333-8	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

# **Marking Information**



N25 = Product Type Marking Code YYWW = Date Code Marking YY = Last digit of year (ex: 11 = 2011) WW = Week code (01 ~ 53)

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DMN3025LFG

## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage			$V_{DSS}$	30	V
Gate-Source Voltage			$V_{GSS}$	±20	V
Continuous Prais Current (Note EVV - 40V	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +70°C	I <sub>D</sub>	7.5 6.1	А
Continuous Drain Current (Note 5) V <sub>GS</sub> = 10V	t<10s	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I <sub>D</sub>	10 7.8	А
Maximum Continuous Body Diode Forward Current (Note 5)			I <sub>S</sub>	2.5	Α
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I <sub>DM</sub>	60	Α
Avalanche Current (Note 6) L = 0.1mH			I <sub>AR</sub>	14	Α
Avalanche Energy (Note 6) L = 0.1mH			E <sub>AR</sub>	10	mJ

## **Thermal Characteristics**

Characteristic	_	Symbol	Value	Units	
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	D-	2.0	W	
Total Fower Dissipation (Note 5)	T <sub>A</sub> = +70°C	P <sub>D</sub>	1.3	VV	
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	61		
Thermal Resistance, Junction to Ambient (Note 5)	t < 10s	$R_{\theta JA}$	37	°C/W	
Thermal Resistance, Junction to Case	$R_{ heta JC}$	6.4			
Operating and Storage Temperature Range		$T_{J_1}T_{STG}$	-55 to 150	°C	

# Electrical Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	_	_	1	μA	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±1	μA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(th)</sub>	8.0	_	2.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	
Static Drain-Source On-Resistance		-	14	18	mΩ	$V_{GS} = 10V, I_D = 7.8A$	
Static Dialii-Source Off-Resistance	R <sub>DS (ON)</sub>	-	23	28	111 2 2	$V_{GS} = 4.5V, I_D = 7.0A$	
Forward Transfer Admittance	Y <sub>fs</sub>	_	9	-	S	$V_{DS} = 10V, I_D = 7.8A$	
Diode Forward Voltage	$V_{SD}$	_	0.70	1.0	V	$V_{GS} = 0V, I_S = 6.3A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	C <sub>iss</sub>	_	605	_		V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Output Capacitance	Coss	_	74	_	pF		
Reverse Transfer Capacitance	C <sub>rss</sub>	_	58	_			
Gate resistance	$R_g$	_	1.5	_	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$	
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	5.3	_		V <sub>DS</sub> = 15V, I <sub>D</sub> = 7.8A	
Total Gate Charge (V <sub>GS</sub> = 10V)	$Q_g$	_	11.6	_	nC		
Gate-Source Charge	$Q_{gs}$	_	2	_	IIC		
Gate-Drain Charge	$Q_{gd}$	_	2.4	_			
Turn-On Delay Time	t <sub>D(on)</sub>	_	3.8	_		$V_{DD}$ = 15V, $V_{GS}$ = 4.5V, $R_{L}$ = 2.4 $\Omega$ , $R_{G}$ = 1 $\Omega$ ,	
Turn-On Rise Time	t <sub>r</sub>	_	4.1	_			
Turn-Off Delay Time	t <sub>D(off)</sub>	_	17.9	_	ns		
Turn-Off Fall Time	t <sub>f</sub>	_	4.7	_			
Reverse Recovery Time	t <sub>rr</sub>	_	5.5	_	ns	L = 124 di/dt = 5004/::s	
Reverse Recovery Charge	Qrr	_	2.6	_	nC	$I_F = 12A$ , di/dt = 500A/ $\mu$ s	

5. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

6. l<sub>AR</sub> and E<sub>AR</sub> rating are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C 7. Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.

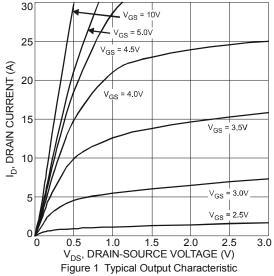
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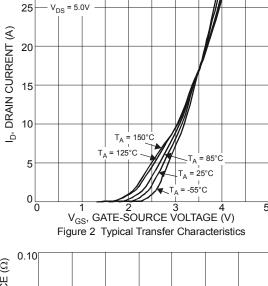
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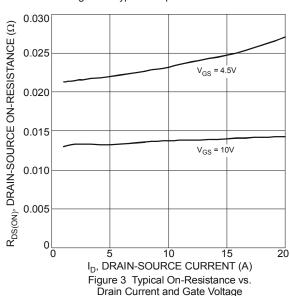
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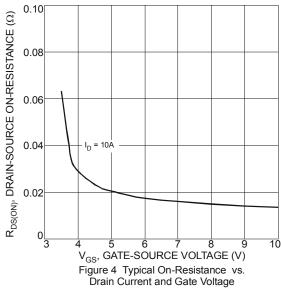


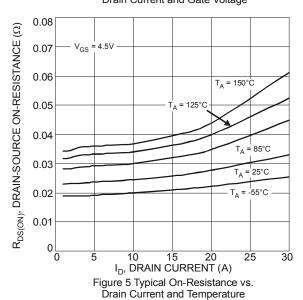
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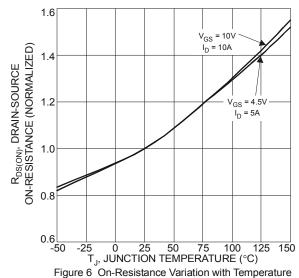












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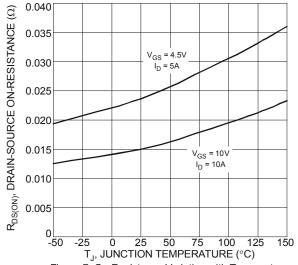


Figure 7 On-Resistance Variation with Temperature

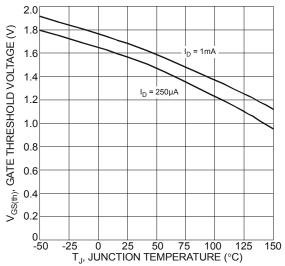
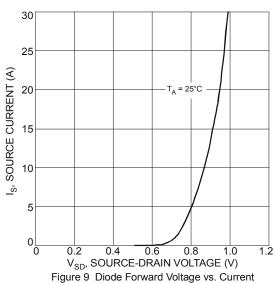
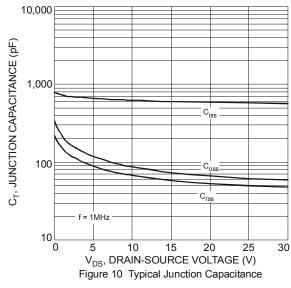
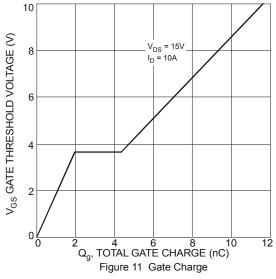
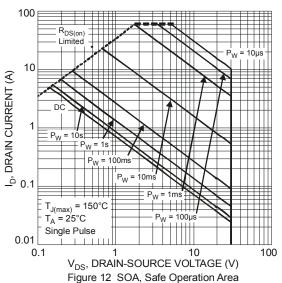


Figure 8 Gate Threshold Variation vs. Ambient Temperature







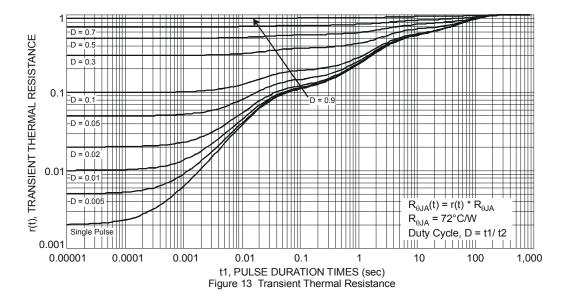


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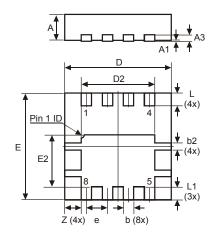


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# **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.

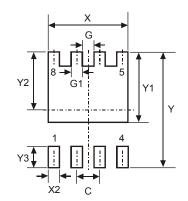


POWERDI3333-0					
Dim	Min	Max	Тур		
D	3.25	3.35	3.30		
Е	3.25	3.35	3.30		
D2	2.22	2.32	2.27		
E2	1.56	1.66	1.61		
Α	0.75	0.85	0.80		
A1	0	0.05	0.02		
A3	_	_	0.203		
b	0.27	0.37	0.32		
b2	_	_	0.20		
L	0.35	0.45	0.40		
L1	_	_	0.39		
е	_	_	0.65		
Z	_	_	0.515		
All Dimensions in mm					

POWERDI3333-8

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)		
С	0.650		
G	0.230		
G1	0.420		
Υ	3.700		
Y1	2.250		
Y2	1.850		
Y3	0.700		
Х	2.370		
X2	0.420		

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